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## Call for Papers



# 2021 IEEE International Conference on ICEDA 2021

Electron Devices and Applications  
2021 年 IEEE 电子器件与应用国际会议

[www.iceda.org](http://www.iceda.org)

Nanjing, China | August 14-16, 2021

## Keynote Speakers

演讲嘉宾



**Prof. Juin J. Liou (FIEEE)**, Shenzhen University, China  
刘俊杰教授, 深圳大学

**Prof. Xiaoqing Wen (FIEEE)**, Kyushu Institute of Technology, Japan

温晓青教授, 日本九州工业大学



**Prof. Daohua Zhang (FInstP, FIET)**, Nanyang Technological University, Singapore

Daohua Zhang 教授, 新加坡南洋理工大学



**Prof. Shumin Xiao**, Harbin Institute of Technology, Shenzhen, China  
肖淑敏教授, 哈尔滨工业大学 (深圳)

演讲嘉宾

## Invited Speakers

## Topics

征稿主题

- CMOS platform technologies / Logic device performance and circuit design challenges / Advanced process integration schemes and scaling approaches / Process module and process control advancements / Device technology co-optimization solutions / SiGe/Ge channel, GAA nanowire and stacked nanosheet / Stacked and monolithic 3D integration / BEOL compatible transistors, etc
- CMOS平台技术/逻辑器件性能和电路设计挑战/先进的工艺集成方案和缩放方法/工艺模块和工艺控制方面的进步/器件技术共同优化解决方案/ SiGe / Ge 通道, GAA 纳米线和堆叠的纳米片/堆叠和单片 3D 集成 / BEOL 兼容晶体管等

## Contact us

联系我们

- Ms. Ariel Xie
- +86-13103333332  
(GMT+8 - Monday- Friday / 09:30-18:00)
- [icedaconf@vip.163.com](mailto:icedaconf@vip.163.com)

## Committee

组委会

- **Advisory Committee Chair**  
Prof. Daohua Zhang (FInstP, FIET), Nanyang Technological University, Singapore
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Prof. Wei Lei, Southeast University, China
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Prof. Letian Huang, University of Electronic Science and Technology of China  
Dr. Jianying Wei, Anlogic, China
- **Publication Chair**  
Hong Guo, Dalian University of Technology, China

## Publication

出版

- Accepted papers will be published into ICEDA conference proceedings by IEEE. The proceedings will be submitted for inclusion into **IEEE Xplore**, **Ei Compendex** and **Scopus**.
- 本次大会接收的文章将出版在 IEEE 会议论文集, 会后提交至 IEEE 数据库收录并实现 Ei 核心和 Scopus 检索。

## Submission

投稿

- **Online Submission:**  
<https://easychair.org/conferences/?conf=iceda2021>  
(You will need an account to log in)
- **Email Submission:** [icedaconf@vip.163.com](mailto:icedaconf@vip.163.com)

## Key Dates

重要日期

Submission Deadline 投稿截止日期	March 15, 2021
Notification of Result 录用通知日期	April 15, 2021
Registration Deadline 注册截止日期	April 25, 2021